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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
TAE WON KIM	02/07/2007
KYEONG TAE LEE	02/07/2007
ALEXANDER PATERSON	02/07/2007
VALENTIN N. TODOROV	02/07/2007
SHASHANK C. DESHMUKH	02/13/2007

RECEIVING PARTY DATA

Name:	APPLIED MATERIALS, INC.	
Street Address:	et Address: P.O. BOX 450A	
Internal Address:	LEGAL AFFAIRS DEPT.	
City:	SANTA CLARA	
State/Country:	CALIFORNIA	
Postal Code:	95052	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	11678047

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER: AM11506-03/ETCH/MDD

PATENT REEL: 018924 FRAME: 0294

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NAME OF SUBMITTER: ROBERT W. MULCAHY

Total Attachments: 2

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> PATENT REEL: 018924 FRAME: 0295

ASSIGNMENT FOR APPLICATION FOR PATENT

WHEREAS:

Names and Addresses of Inventors:

1)	Tae Won Kim 754 The Alameda #3213 San Jose, CA 95126	2)	Kyeong-Tae Lee 619 Bolton Ct. #6 San Jose, CA 95129
3)	Alexander Paterson 7268 Martwood Way San Jose, CA 95120	4)	Valentin N. Todorov 2473 Emerson Street Palo Alto, CA 94301
5)	Shashank C. Deshmukh 2168 Pettigrew Drive San Jose, CA 95148		

(hereinafter referred to as Assignors), have invented a certain invention entitled:

PULSED-PLASMA SYSTEM WITH PULSED REACTION GAS REPLENISH FOR ETCHING SEMICONDUCTOR STRUCTURES

for which application	on for Letters Patent in the United States was filed on
under Serial No	, executed on even date herewith; and

WHEREAS, Applied Materials, Inc., a corporation of the State of Delaware, having a place of business at 3050 Bowers Avenue, Santa Clara, California 95054 (hereinafter referred to as Assignee), is desirous of acquiring the entire right, title and interest in and to said application (hereinafter referred to as the Application), and the invention disclosed therein (hereinafter referred to as the Invention), and in and to all embodiments of the Invention, heretofore conceived, made or discovered by said Assignors, and in and to any and all patents, inventor's certificates and other forms of protection (hereinafter referred to as the Patents) thereon granted in any and all countries and groups of countries.

NOW, THEREFORE, in consideration of good and valuable consideration acknowledged by said Assignors to have been received in full from said Assignee:

- 1. Said Assignors hereby sell, assign, transfer and convey to Assignee the full and exclusive right, title and interest (a) in and to said Application and said Invention; (b) in and to all rights to apply for patents on said Invention in any and all countries pursuant to the International Convention for the Protection of Industrial Property or otherwise; (c) in and to any and all Applications filed and any and all Patents granted on said Invention in any and all countries and groups of countries, including each and every Application filed and each and every Patent granted on any application which is a division, substitution, or continuation of said Application; and (d) in and to each and every reissue or extension of any of said Patents.
- 2. Said Assignors hereby covenant and agree to cooperate with said Assignee to enable said Assignee to enjoy to the fullest extent the right, title and interest to said Invention herein conveyed in any and all countries and groups of countries. Such cooperation by said Assignors shall include prompt production of pertinent facts and documents, giving testimony, execution of petitions, oaths, specifications, declarations or other papers, and other assistance all to the extent deemed necessary or desirable by said Assignee (a) for perfecting in said Assignee the right, title and interest herein conveyed; (b) for prosecuting any of said applications; (c) for filing and prosecuting substitute, divisional, continuing or

PATENT REEL: 018924 FRAME: 0296 additional applications covering said Invention; (d) for filing and prosecuting applications for reissuance of any of said Patents; (e) for interference or other priority proceedings involving said Invention; and (f) for legal proceedings involving said Invention and any application therefor and any Patents granted thereon, including without limitation opposition proceedings, cancellation proceedings, priority contests, public use proceedings, infringement actions and court actions; provided, however, that the expense incurred by said Assignors in providing such cooperation shall be paid for by said Assignee.

- 3. The term and covenants of this agreement shall inure to the benefit of said Assignee, its successors, assigns and other legal representatives, and shall be binding upon said Assignors, their respective heirs, legal representatives and assigns.
- 4. Said Assignors hereby warrant and represent that they have not entered and will not enter into any assignment, contract, or understanding in conflict herewith.

IN WITNESS WHEREOF, the said Assignors have executed and delivered this instrument to said

Assignee on the dates indicated below.

- 1) 02/62, 2007
- 2) 02/07 , 2007
- 3) <u>2/7/c7</u>; 2007
- 4) 02.07,2007
- 2 13 2007

Tae Won Kim

lexander Paterson

Valentin N. Todorov

Shashank C. Deshmukh

RECORDED: 02/22/2007